

# P-Channel Enhancement-Mode **Vertical DMOS FETs**

#### **Features**

- Free from secondary breakdown
- Low power drive requirement
- Ease of paralleling
- Low C<sub>ISS</sub> and fast switching speeds
- Excellent thermal stability
- Integral source-drain diode
- High input impedance and high gain

#### **Applications**

- Motor controls
- Converters
- **Amplifiers**
- Switches
- Power supply circuits
- Drivers (relays, hammers, solenoids, lamps, memories, displays, bipolar transistors, etc.)

#### General Description

This enhancement-mode (normally-off) transistor utilizes a vertical DMOS structure and Supertex's well-proven, silicon-gate manufacturing process. This combination produces a device with the power handling capabilities of bipolar transistors and the high input impedance and positive temperature coefficient inherent in MOS devices. Characteristic of all MOS structures, this device is free from thermal runaway and thermally-induced secondary breakdown.

Supertex's vertical DMOS FETs are ideally suited to a wide range of switching and amplifying applications where very low threshold voltage, high breakdown voltage, high input impedance, low input capacitance, and fast switching speeds are desired.

#### Ordering Information

Part Number	Package Option	Packing
VP0106N3-G	TO-92	1000/Bag
VP0106N3-G P002		
VP0106N3-G P003		
VP0106N3-G P005	TO-92	2000/Reel
VP0106N3-G P013		
VP0106N3-G P014		

<sup>-</sup>G denotes a lead (Pb)-free / RoHS compliant package. Contact factory for Wafer / Die availablity.

Devices in Wafer / Die form are lead (Pb)-free / RoHS compliant.

### Absolute Maximum Ratings

Parameter	Value
Drain-to-source voltage	BV <sub>DSS</sub>
Drain-to-gate voltage	$BV_{DGS}$
Gate-to-source voltage	±20V
Operating and storage temperature	-55°C to +150°C

Absolute Maximum Ratings are those values beyond which damage to the device may occur. Functional operation under these conditions is not implied. Continuous operation of the device at the absolute rating level may affect device reliability. All voltages are referenced to device ground.

### **Typical Thermal Resistance**

Package	$\theta_{ja}$
TO-92	132°C/W

### **Product Summary**

BV <sub>DSS</sub> /BV <sub>DGS</sub>	R <sub>DS(ON)</sub> (max)	l <sub>D(ON)</sub> (min)
-60V	00.8	-500mA

#### **Pin Configuration**



#### **Product Marking**



YY = Year Sealed WW = Week Sealed \_ = "Green" Packaging

Package may or may not include the following marks: Si or \$\infty\$



#### **Thermal Characteristics**

Package	l <sub>D</sub> (continuous) <sup>†</sup>	l <sub>□</sub> (pulsed)	Power Dissipation @T <sub>c</sub> = 25°C	l <sub>DR</sub> †	l DRM
TO-92	-250mA	-800mA	1.0W	-250mA	-800A

#### Notes:

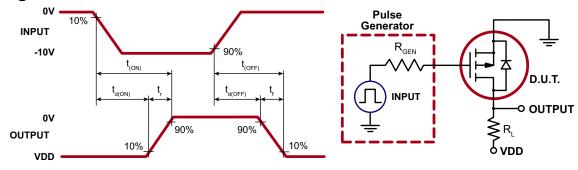
# **Electrical Characteristics** ( $T_A = 25$ °C unless otherwise specified)

Sym	Parameter	Min	Тур	Max	Units	Conditions	
BV <sub>DSS</sub>	Drain-to-source breakdown voltage	-60	-	-	V	$V_{GS} = 0V, I_{D} = -1.0 \text{mA}$	
$V_{GS(th)}$	Gate threshold voltage	-1.5	-	-3.5	V	$V_{GS} = V_{DS}$ , $I_{D} = -1.0$ mA	
$\Delta V_{GS(th)}$	Change in V <sub>GS(th)</sub> with temperature	_	5.8	6.5	mV/°C	$V_{GS} = V_{DS}$ , $I_{D} = -1.0$ mA	
l <sub>GSS</sub>	Gate body leakage current	-	-1.0	-100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
		-	-	-10	μA	$V_{GS} = 0V, V_{DS} = Max Rating$	
I <sub>DSS</sub>	Zero gate voltage drain current	-	-	-1.0	mA	$V_{DS} = 0.8$ Max Rating, $V_{GS} = 0V$ , $T_{A} = 125^{\circ}C$	
	On state duals surrent	-0.15	-0.25	-		$V_{GS} = -5.0V, V_{DS} = -25V$	
I <sub>D(ON)</sub>	On-state drain current	-0.5	-1.2	-	Α	V <sub>GS</sub> = -10V, V <sub>DS</sub> = -25V	
D	Static drain-to-source	-	11	15		$V_{GS} = -5.0V, I_{D} = -100mA$	
R <sub>DS(ON)</sub>	on-state resistance	-	6.0	8.0	Ω	V <sub>GS</sub> = -10V, I <sub>D</sub> = -500mA	
$\Delta R_{DS(ON)}$	Change in R <sub>DS(ON)</sub> with temperature	-	0.55	1.0	%/°C	$V_{GS} = -10V, I_{D} = -500 \text{mA}$	
G <sub>FS</sub>	Forward transconductance	150	190	-	mmho	$V_{DS} = -25V, I_{D} = -500mA$	
C <sub>ISS</sub>	Input capacitance	-	45	60		V <sub>GS</sub> = 0V,	
C <sub>oss</sub>	Common source output capacitance	-	22	30	pF	$V_{DS} = -25V,$	
$C_{RSS}$	Reverse transfer capacitance	-	3.0	8.0		f = 1.0MHz	
t <sub>d(ON)</sub>	Turn-on delay time	-	4.0	6.0			
t <sub>r</sub>	Rise time	-	3.0	10	ns	$V_{DD} = -25V,$	
t <sub>d(OFF)</sub>	Turn-off delay time	-	8.0	12		$I_D = -500 \text{mA},$ $R_{GEN} = 25\Omega$	
t <sub>f</sub>	Fall time	-	4.0	10		GEN -	
$V_{SD}$	Diode forward voltage drop	-	-1.2	-2.0	V	V <sub>GS</sub> = 0V, I <sub>SD</sub> = -1.0A	
t <sub>rr</sub>	Reverse recovery time	-	400	-	ns	$V_{GS} = 0V, I_{SD} = -1.0A$	

#### Notes:

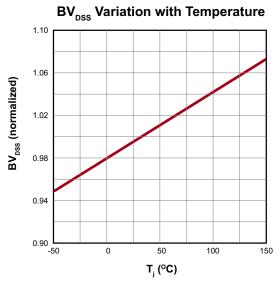
- 1. All D.C. parameters 100% tested at 25°C unless otherwise stated. (Pulse test: 300µs pulse, 2% duty cycle.)
- 2. All A.C. parameters sample tested.

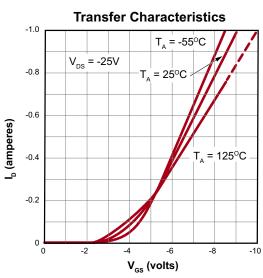
# **Switching Waveforms and Test Circuit**

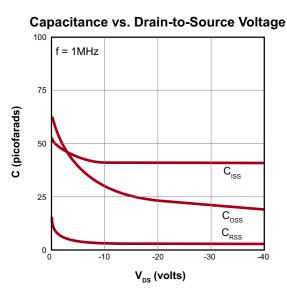


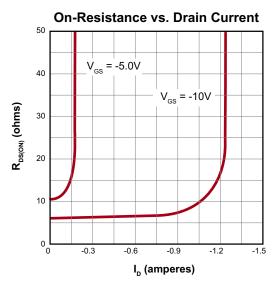
<sup>†</sup>  $I_D$  (continuous) is limited by max rated  $T_i$ .

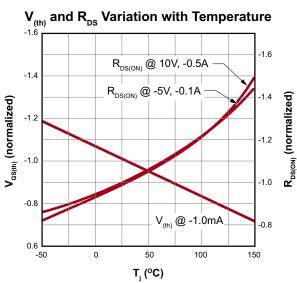
#### **Typical Performance Curves**

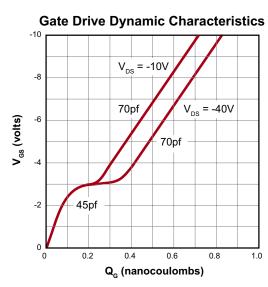




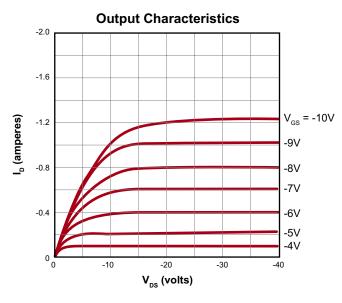


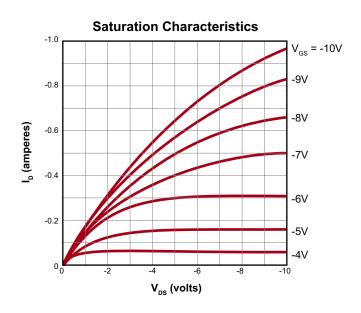


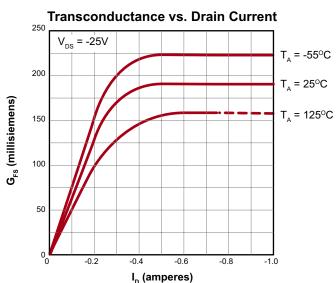


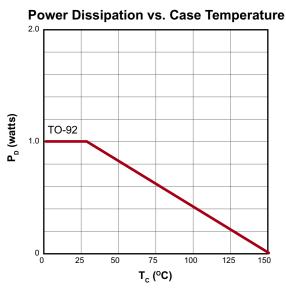


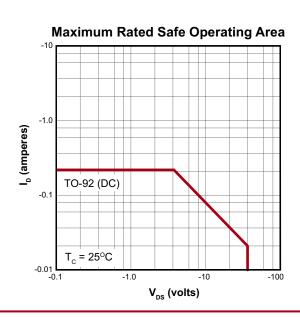
#### **Typical Performance Curves** (cont.)

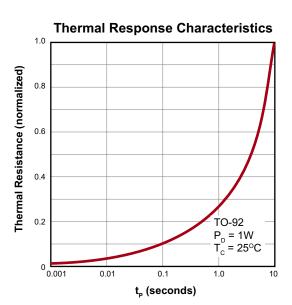




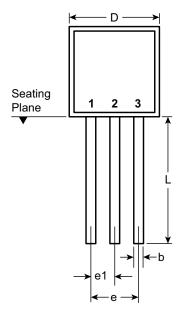


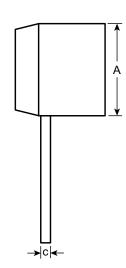






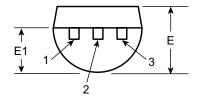
# 3-Lead TO-92 Package Outline (N3)





**Front View** 

**Side View** 



**Bottom View** 

Symb	ol	Α	b	С	D	E	E1	е	e1	L
	MIN	.170	.014 <sup>†</sup>	.014 <sup>†</sup>	.175	.125	.080	.095	.045	.500
Dimensions (inches)	NOM	-	-	-	-	-	-	-	-	-
(inches)	MAX	.210	.022 <sup>†</sup>	.022 <sup>†</sup>	.205	.165	.105	.105	.055	.610*

JEDEC Registration TO-92.

Drawings not to scale.

Supertex Doc.#: DSPD-3TO92N3, Version E041009.

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to <a href="http://www.supertex.com/packaging.html">http://www.supertex.com/packaging.html</a>.)

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<sup>\*</sup> This dimension is not specified in the JEDEC drawing.

<sup>†</sup> This dimension differs from the JEDEC drawing.